

DDR2 SDRAM PART NUMBERING

H5PSXXXX-XX													
1234				5678				91011				121314	
HYNIX MEMORY				OPERATING TEMPERATURE & POWER CONSUMPTION									
PRODUCT FAMILY				C : Commercial Temp ¹⁾ & Normal Power									
5 : DRAM				L : Commercial Temp ¹⁾ & Low Power									
PRODUCT MODE				E : Extended Temp ²⁾ & Normal Power									
P : DDR2 SDRAM				I : Industrial Temp ³⁾ & Normal Power									
POWER SUPPLY				SPEED(tCL-tRCD-tRP)									
S : VDD=1.8V & VDDQ=1.8V				G7 : DDR2-1066 7-7-7									
G : VDD=1.55V & VDDQ=1.55V				G6 : DDR2-1066 6-6-6									
DENSITY & REFRESH				S6 : DDR2-800 6-6-6									
25 : 256Mb 8K/64ms Refresh				S5 : DDR2-800 5-5-5									
51 : 512Mb 8K/64ms Refresh				Y5 : DDR2-667 5-5-5									
1G : 1Gb 8K/64ms Refresh				Y4 : DDR2-667 4-4-4									
2G : 2Gb 8K/64ms Refresh				C4 : DDR2-533 4-4-4									
4G : 4Gb 8K/64ms Refresh				E3 : DDR2-400 3-3-3									
ORGANIZATION				PACKAGE MATERIAL									
4 : x4				L : Lead									
8 : x8				P : Lead free (ROHS ⁴⁾ compliant)									
6 : x16				R : Lead Free & Halogen Free (ROHS ⁴⁾ compliant)									
NUMBER OF BANKS				PACKAGE TYPE									
2 : 4 Banks				F : FBGA SDP (Single Die Package)									
3 : 8 Banks				M : FBGA DDP (Dual Die Package)									
				H : FBGA QDP (Quad Die Package)									
				DIE GENERATION									
				M : 1st					D : 5th				
				A : 2nd				E : 6th					
				B : 3rd				F : 7th					
				C : 4th				G : 8th					

Note:

- 1) Commercial Temperature: 0°C ~ 85°C
- 2) Extended Temperature: -25°C ~ 85°C
- 3) Industrial Temperature: -40°C ~ 85°C
- 4) ROHS : Restriction Of Hazardous Substances

DDR2 SDRAM PART NUMBERING

HYXXX XX XX X X X X X - XX X													
HYNIX MEMORY										TEMPERATURE			
										I : Industrial (-40℃~85℃) E : Extended (-25℃~85℃)			
PRODUCT FAMILY										SPEED			
										S6 : DDR2-800 6-6-6 S5 : DDR2-800 5-5-5 Y6 : DDR2-667 6-6-6 Y5 : DDR2-667 5-5-5 Y4 : DDR2-667 4-4-4 C5 : DDR2-533 5-5-5 C4 : DDR2-533 4-4-4 C3 : DDR2-533 3-3-3 E4 : DDR2-400 4-4-4 E3 : DDR2-400 3-3-3			
PROCESS & POWER SUPPLY										PACKAGE MATERIAL			
										BLANK : Normal P : Lead free(ROHS* Compliant) R : Lead & Halogen free (ROHS* Compliant)			
DENSITY & REFRESH										PACKAGE TYPE			
										F : FBGA Single Die S : FBGA Stack M : FBGA DDP (Dual Die Package)			
ORGANIZATION										POWER CONSUMPTION			
										BLANK : Normal L : Low Power K : Reduced Power			
# of BANK													
INTERFACE													
DIE GENERATION													

5P	: DDR2 SDRAM
S	: VDD=1.8V & VDDQ=1.8V
28	: 128M 4K Refresh
56	: 256M 8K Refresh
12	: 512M 8K Refresh
1G	: 1G 8K Refresh
2G	: 2G 8K Refresh
4	: x4
8	: x8
16	: x16
32	: x32
1	: 2Banks
2	: 4Banks
3	: 8Banks
1	: SSTL_18
2	: SSTL_2
BLANK	: 1st Gen.
A	: 2nd Gen.
B	: 3rd Gen.
C	: 4th Gen.

* ROHS : Restriction Of Hazardous Substances

** All DDR2 SDRAMs follow above Part Numbering System